2SJ0674

Silicon P-channel MOS FET

For switching circuits

■ Features

- Low ON resistance Ron
- High-speed switching
- SSSMini type package, allowing downsizing of the equipment and automatic insertion through the tape packing

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Drain-source surrender voltage	V _{DSS}	-30	V
Gate-source surrender voltage	V _{GSS}	±12	V
Drain current	I_{D}	-100	mA
Peak drain current	I_{DP}	-200	mA
Power dissipation	P _D	100	mW
Channel temperature	T_{ch}	125	°C
Storage temperature	T _{stg}	-55 to +125	°C
	sig		

Package

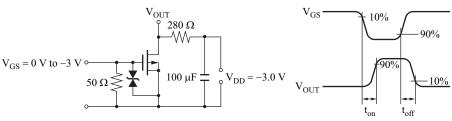
- Code
- SSSMini3-F1
- Pin Name

■ Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

• SSSMini type package, allowing of	lownsizing o	f the equipme	ant and				
and the second of the second	_	i the equipm	ent and	Pin Name			<u> </u>
automatic insertion through the tape pa	cking			1: Gate			Ø.
Absolute Marierum Detiene E	2500			2: Source		CX'O	
■ Absolute Maximum Ratings T ₂				3: Drain	<u> </u>	(e)	
Parameter	Symbol	Rating	Unit	Marking Sv	mbok 50)	
Drain-source surrender voltage	V _{DSS}	-30	V	Ivial King Syl	, <u>k</u> (
Gate-source surrender voltage	V _{GSS}	±12	V	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \			
Drain current	I_{D}	-100	mA	AUC			
Peak drain current	I_{DP}	-200	mA	2500			
Power dissipation	P _D	100	Unit V V MA MA MW C C C C C C C C C C C C C	" X			
Channel temperature	T_{ch}	125	°C 40	S.			·01.
Storage temperature	T _{stg}	-55 to +125	C C	18		2	
+ •			1/1/ ce	ζ, δ		M	
■ Electrical Characteristics $T_a = 2$	25°C±3°C		i allo ano	10° 10°	•.4	40.	
Parameter	Symbo	ı	Conditions	Min	Тур	Max	Unit
Drain-source surrender voltage	V _{DSS}	$I_{\rm D} = -10 \mu$	1, V _{GS} = 0	Je 1930	XO .		V
Drain-source cutoff current	$I_{ m DSS}$	V _{DS} = -20	$VV_{GS} = 0$	7 73 17	20/6	-1.0	μΑ
Gate-source cutoff current	I _{GSS}	$V_{GS} = \pm 10$		180,000	1/2	±10	μΑ
Gate threshold voltage	V		$A_{\rm V}V_{\rm DS} = 3.0 \rm V$	-0.5	-1.0	-1.5	V
Drain-source ON resistance	in	$I_{\rm D} = -10 \rm m$	$A, V_{GS} = -2.5 V$	5 110	13	30	
	R _{DS(on)}	$I_{\rm D} = -10 \rm m$	N. S. S.	, co	9	10	Ω
		1 10 10 10	$A, V_{GS} = -4.0 \text{ V}$	05	'	18	22
Forward transfer admittance	Y _{fs}			Hz 20	40	18	mS
Short-circuit input capacitance			$A, V_{GS} = -4.0 \text{ V}$ $A, V_{DS} = -3 \text{ V}, f = 1 \text{ K}$	12 20		18	mS
Short-circuit input capacitance (Common source)	Y _{fs} C _{iss}	$I_D = -10 \mathrm{m}$	$A, V_{DS} = -3 \text{ V, } f = 1 \text{ k}$	20	40	18	
Short-circuit input capacitance (Common source) Short-circuit output capacitance		$I_D = -10 \mathrm{m}$	$A, V_{DS} = -3 \text{ V, } f = 1 \text{ k}$	20	40	18	mS
Short-circuit input capacitance (Common source) Short-circuit output capacitance (Common source)	C _{iss}	$I_D = -10 \mathrm{m}$		20	40	18	mS pF
Short-circuit input capacitance (Common source) Short-circuit output capacitance	C _{iss}	$I_D = -10 \mathrm{m}$	$A, V_{DS} = -3 \text{ V, } f = 1 \text{ k}$	20	40	18	mS pF
Short-circuit input capacitance (Common source) Short-circuit output capacitance (Common source) Reverse transfer capacitance	C _{iss}	$I_{D} = -10m$ $V_{DS} = -3$	$A, V_{DS} = -3 \text{ V, } f = 1 \text{ k}$		40 12 13	18	mS pF pF

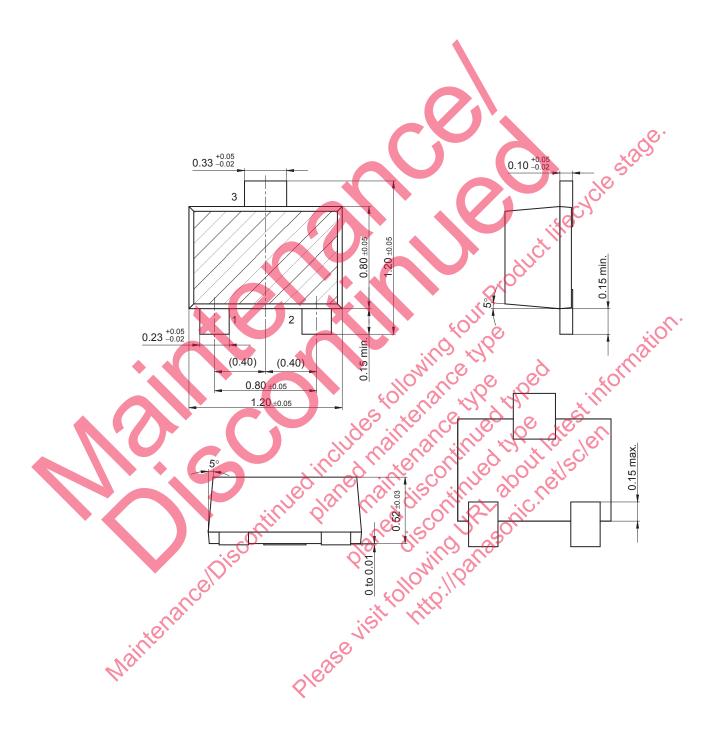
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. * : t_{on} , t_{off} measurement circuit



SSSMini3-F1

Unit: mm



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